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# **162 cable assembly 162 A-D Annexes (TBDs)**

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# Purpose

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- **Proposals for 162 cable assembly and 162 Annexes A-D TBDs**
- **Changes to MTF IL and RL limits**

# Cable Assembly (TBDs)

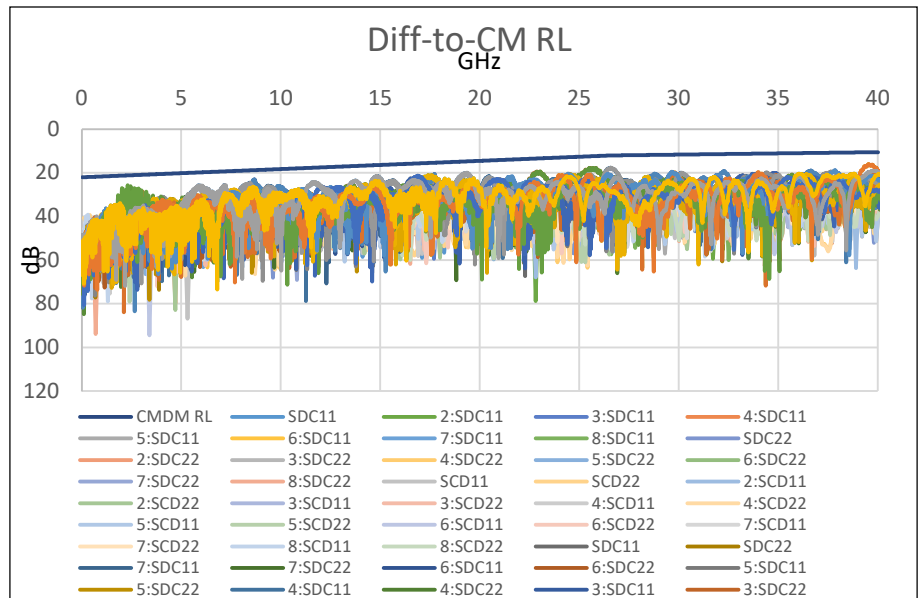
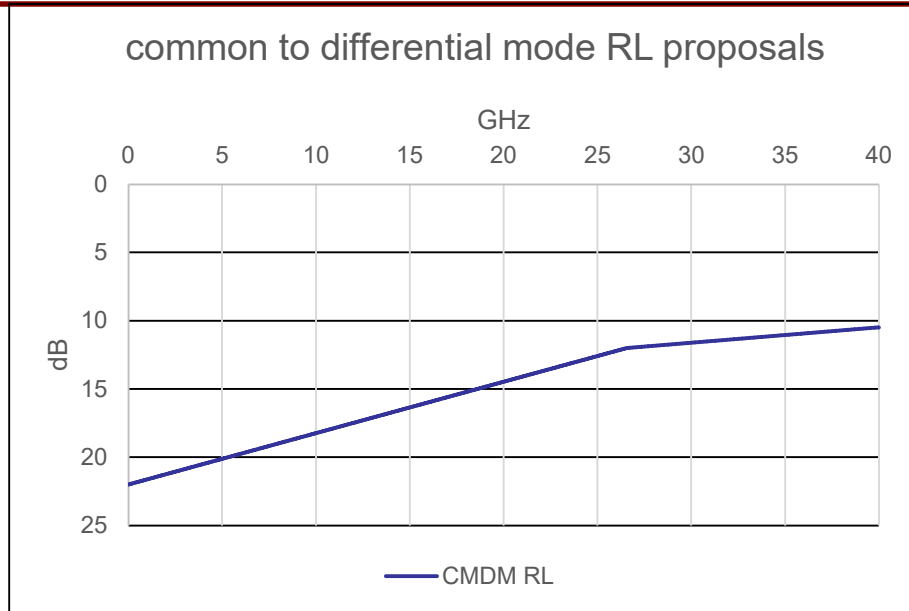
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Table 162–16—Cable assembly characteristics summary

Description	Reference	Value	Unit
Maximum insertion loss at 26.56 GHz	162.11.2	19.75	dB
Minimum insertion loss at 26.56 GHz	162.11.2	11	dB
Minimum cable assembly ERL <sup>a</sup>	162.11.3	TBD	dB
Differential to common-mode return loss	162.11.4	TBD	dB
Differential to common-mode conversion loss	162.11.5	TBD	dB
Common-mode to common-mode return loss	162.11.6	Equation (162–9)	dB
Minimum COM	162.11.7	3	dB

<sup>a</sup>Cable assemblies with a COM greater than 4 dB are not required to meet minimum ERL.

# 162.11.4 Cable Assembly DC RL



$$\text{CDRL}(f) \geq 22 - 10 \cdot f / 26.56, 0.05 \leq f \leq 26.56$$

$$15 - 3 \cdot f / 26.56, 26.56 < f \leq 40$$

Where

f is the frequency in GHz

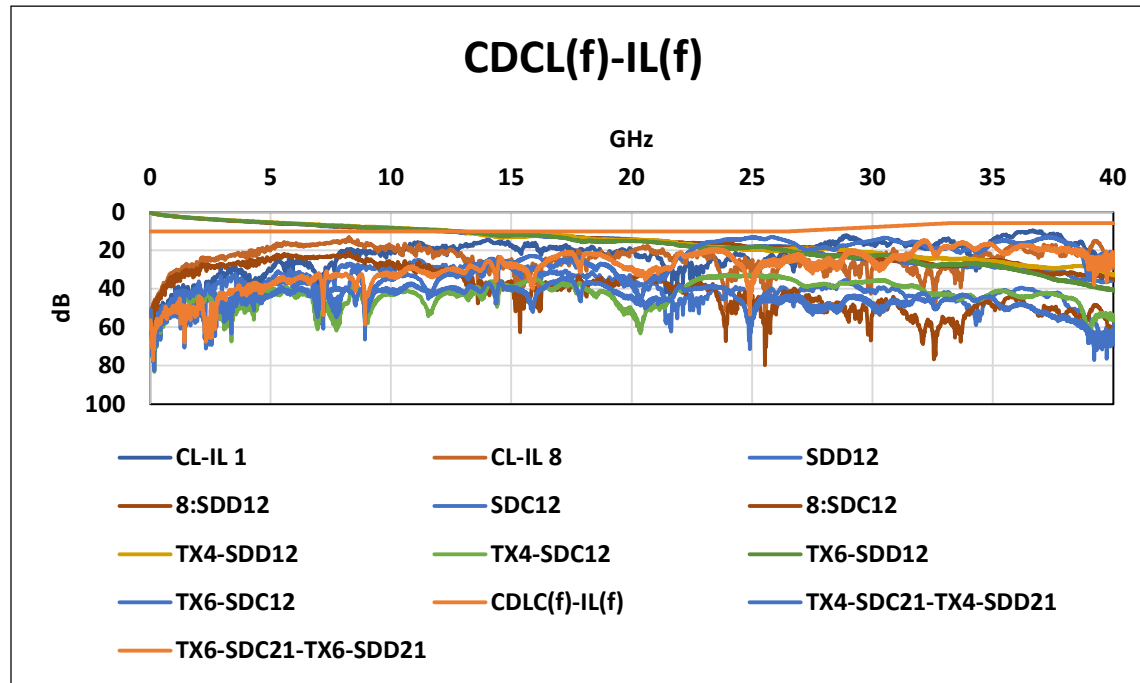
[https://www.ieee802.org/3/ck/public/19\\_07/tracy\\_3ck\\_01b\\_0719.pdf](https://www.ieee802.org/3/ck/public/19_07/tracy_3ck_01b_0719.pdf)

100 Gbps Copper Cable Measurement and S-Parameter File  
8 Channel Cable Measurement

[https://www.ieee802.org/3/ck/public/tools/cucable/matoglu\\_3ck\\_adhoc\\_01\\_030420\\_channels.zip](https://www.ieee802.org/3/ck/public/tools/cucable/matoglu_3ck_adhoc_01_030420_channels.zip)

Cu Cable Channels  
OSFP112G 2m Cable Assembly Measurements  
Update  
Measured OSFP 2m 25awg Cable  
4-March-2020 Erdem MatogluAmphenol ICC

# 162.11.5 Cable Assembly CDCL



[https://www.ieee802.org/3/ck/public/19\\_07/tracy\\_3ck\\_01b\\_0719.pdf](https://www.ieee802.org/3/ck/public/19_07/tracy_3ck_01b_0719.pdf)

100 Gbps Copper Cable Measurement  
and S-Parameter File  
8 Channel Cable Measurement

[https://www.ieee802.org/3/ck/public/tools/cucable/matoglu\\_3ck\\_adhoc\\_01\\_030420\\_channels.zip](https://www.ieee802.org/3/ck/public/tools/cucable/matoglu_3ck_adhoc_01_030420_channels.zip)

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162.11.5 Cable assembly differential to common-mode conversion loss

The difference between the cable assembly differential to common-mode conversion loss and the cable assembly insertion loss shall meet Equation (162-new).

$CDCL(f) - IL(f) \geq$

10,  $0.05 \leq f \leq 26.56$

$27 - 17 * f / 26.56$ ,  $26 < f \leq 33.2$

5.75,  $33.2 < f \leq 40$

Where

f is the frequency in GHz

# Cable Assembly (TBDs)

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## 162.11.2 Cable assembly insertion loss

The measured insertion loss at 26.56 GHz of a cable assembly shall be less than or equal to 19.75 dB.

The measured insertion loss of a cable assembly shall be greater than or equal to the minimum cable assembly insertion loss given in Equation (162–8) and illustrated in Figure 162–4.

$$IL_{\min}(f) \geq 0.418\sqrt{f} + 0.177f + 0.0059f^2 \quad (162-8)$$

for  $\text{TBD} \leq f \leq 40$  GHz    **TBD = 0.05 GHz**

where

$IL_{\min}(f)$             is the minimum cable assembly insertion loss in dB  
 $f$                         is the frequency in GHz

# 162A.4 Tx and Rx differential PCB loss

The recommended maximum and minimum insertion loss allocation for the transmitter or receiver differential controlled impedance printed circuit boards are determined using Equation (162A-1) and Equation (162A-2), respectively, and illustrated in Figure 162A-1. Note that the recommended maximum insertion loss allocation for the transmitter or receiver differential controlled impedance printed circuit boards with allowances for ball grid array (BGA) footprint and host connector footprints is 6.875 dB at 26.56 GHz and the recommended minimum insertion loss allocation for the transmitter or receiver differential controlled impedance printed circuit boards is 2.3 dB at 26.56 GHz.

$$(IL_{PCB}(f) \leq IL_{PCBmax})(f) = IL_{PCBmax}(f_{GHz}) = 0.9809 * (0.471 * \text{SQRT}(f_{GHz}) + 0.1194 * f_{GHz} + 0.002 * (f_{GHz}^2)) \quad (162A-1)$$

for  $0.01 \text{ GHz} \leq f \leq 50 \text{ GHz}$      $IL_{PCBmax}(26.56) = 6.875 \text{ dB}$

where

$IL_{PCB}(f)$

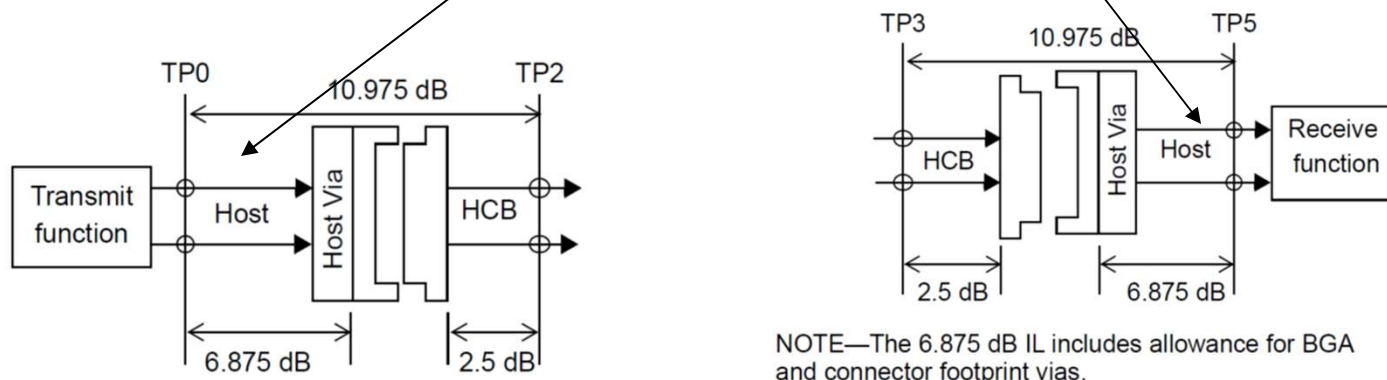
is the insertion loss of the transmitter and receiver PCB in dB

$IL_{PCBmax}(f)$

is the maximum insertion loss of the transmitter and receiver PCB in dB

$f$

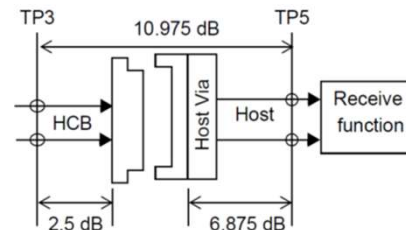
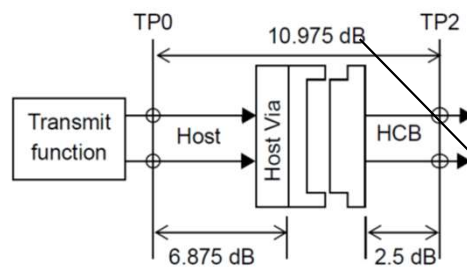
is the frequency in GHz



# 162A.4 IL from TP0 to TP2 or from TP3 to TP5 (host)

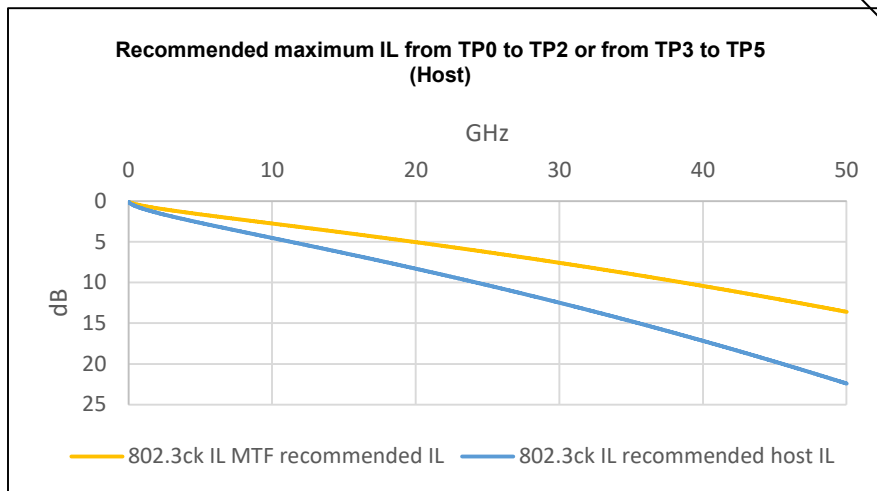
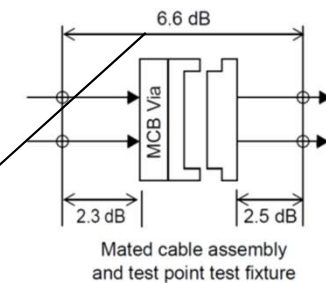
The recommended maximum insertion loss from TP0 to TP2 or from TP3 to TP5 including the test fixture is determined using Equation (162A-3). The recommended maximum insertion loss allocation for the transmitter or receiver differential controlled impedance printed circuit boards is consistent with the insertion loss from TP0 to TP2 or TP3 to TP5 and an assumed mated connector loss of 1.6 dB. Note that the recommended maximum insertion loss from TP0 to TP2 or from TP3 to TP5 is 10.975 dB at 26.56 GHz.

TBD



NOTE—The 6.875 dB IL includes allowance for BGA and connector footprint vias.

(162A-3)



$$IL_{MTF}(f_{GHz}) = 0.9502 * (0.471 * \text{SQRT}(f_{GHz}) + 0.1194 * f_{GHz} + 0.002 * (f_{GHz}^2))$$

$$IL_{MTF}(26.56) = 6.6 \text{ dB}$$

$$IL_{HOST}(f_{GHz}) = 1.5658 * (0.471 * \text{SQRT}(f_{GHz}) + 0.1194 * f_{GHz} + 0.002 * (f_{GHz}^2))$$

$$IL_{HOST}(f_{GHz}) = 10.975 \text{ dB}$$



# 162B.1.3.1 Mated test FOM<sub>ILD</sub>

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- I The FOM<sub>ILD</sub> is calculated according to 93A.4 with  $f_b=53.125$  GHz,  $T_t=7.5$  ps, and  $f_t=0.75 \times f_b$ . The fitted insertion loss and insertion loss deviation are computed over the range  $f_{\min}=0.01$  GHz to  $f_{\max}=40$  GHz. FOM<sub>ILD</sub> shall be less than (TBD) dB.

The reference insertion loss of the mated test fixture is determined using Equation (162B-5).

$$IL_{\text{MatedTF}}(f) = 0.9502(0.471\sqrt{f} + 0.1194f + 0.002f^2) \quad (162B-5)$$

for  $0.01 \text{ GHz} \leq f \leq 50 \text{ GHz}$

where

$IL_{\text{MatedTF}}(f)$  is the reference insertion loss of the mated test fixture insertion loss in dB at frequency  $f$

$f$  is the frequency in GHz

# 162B.1.3.6 Mated test fixtures ICN

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Table 136B-2—SFP28 mated test fixture integrated near-end crosstalk noise voltage

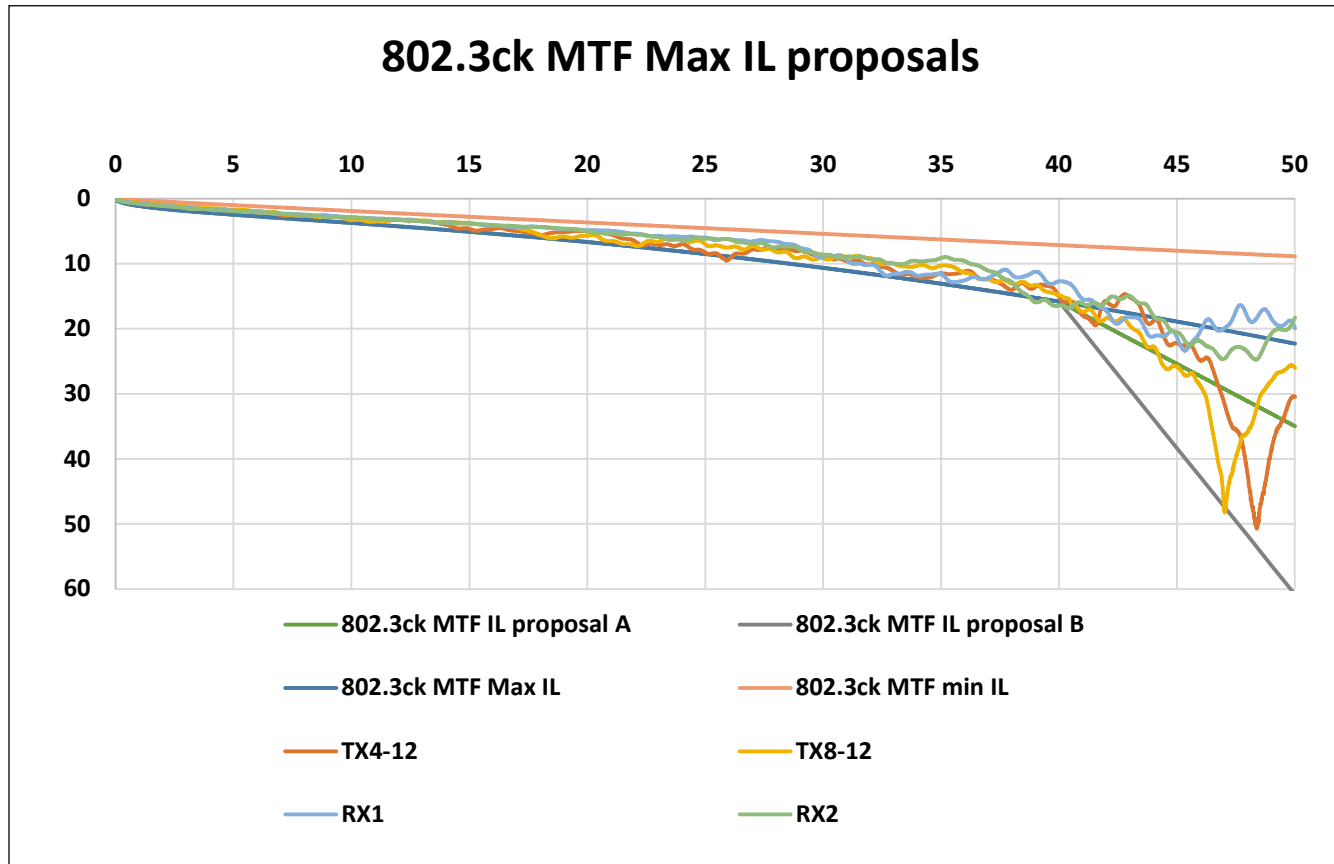
Parameter	Value	Units
Integrated near-end crosstalk noise voltage	Less than 1.6	mV

Table 162B-2—SFP+ mated test fixture integrated near-end crosstalk noise voltage

Parameter	Value	Units
Integrated near-end crosstalk noise voltage	Less than TBD	mV

TBD = 1.6 mV

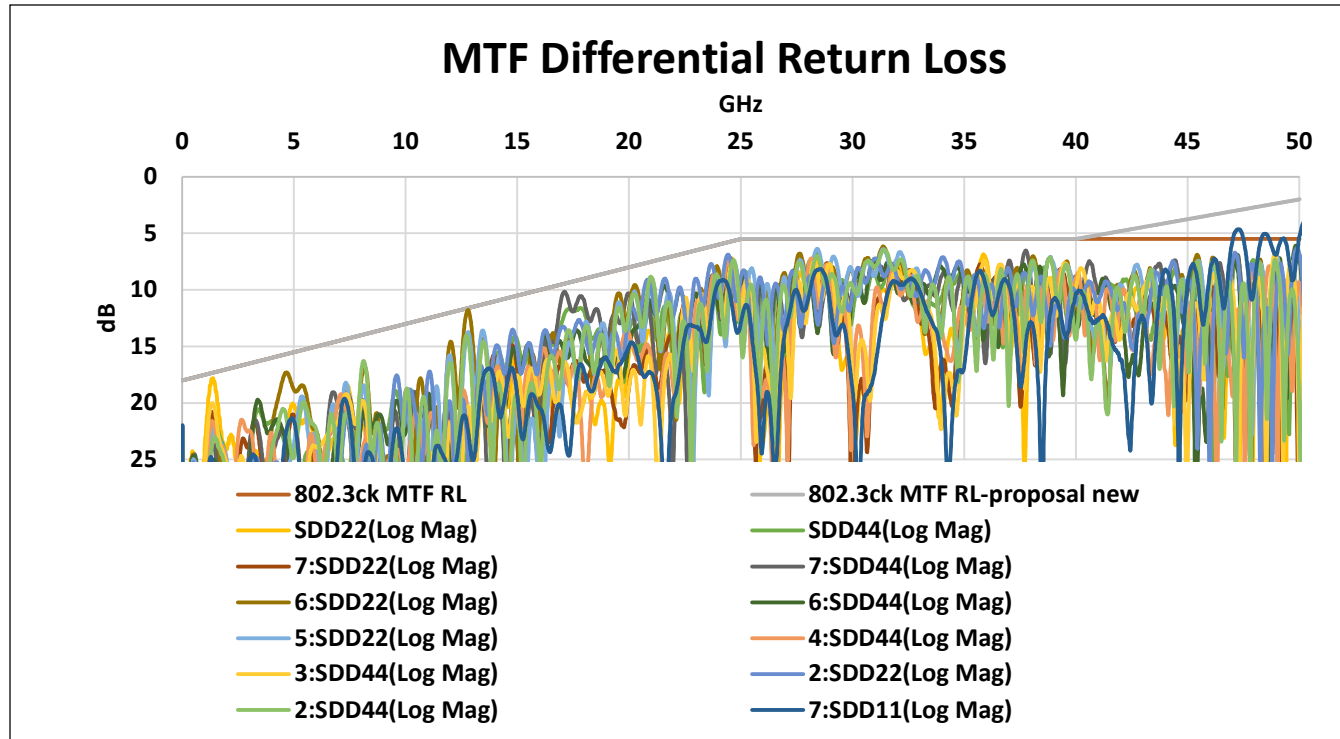
# 162B.1.3.1 Mated test fixtures differential insertion loss



MTF IL proposal A =  $1.185 \cdot \text{SQRT}(f) - 0.072 \cdot f + 0.007 \cdot f^2$        $0.01 \text{ GHz} \leq f < 40 \text{ GHz}$   
 MTF IL proposal A =  $1.915 \cdot f - 60.78$        $40 \text{ GHz} \leq f \leq 50 \text{ GHz}$

MTF IL proposal B =  $1.185 \cdot \text{SQRT}(f) - 0.072 \cdot f + 0.007 \cdot f^2$        $0.01 \text{ GHz} \leq f < 40 \text{ GHz}$   
 MTF IL proposal B =  $4.5 \cdot f - 164.186$        $40 \text{ GHz} \leq f \leq 50 \text{ GHz}$

# 162B.1.3.2 MTF differential return loss



**PROPOSAL: Differential Return Loss =**

$$18 - 0.5 \cdot f_{\text{GHz}} \quad 0.05 \text{ GHz} \leq f_{\text{GHz}} < 25 \text{ GHz}$$

$$5.5 \quad 25 \text{ GHz} \leq f_{\text{GHz}} < 40 \text{ GHz}$$

$$-3.5 \cdot (f_{\text{GHz}} - 40) + 5.5 \quad 40 \text{ GHz} \leq f_{\text{GHz}} \leq 50 \text{ GHz}$$